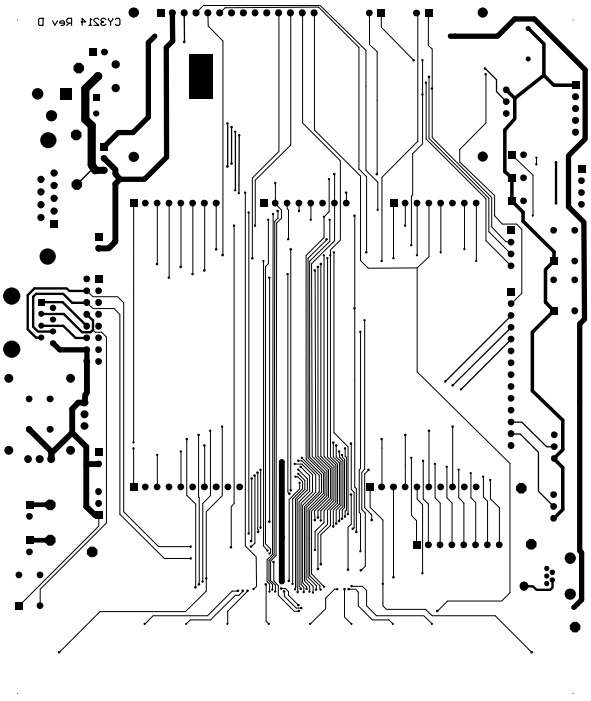
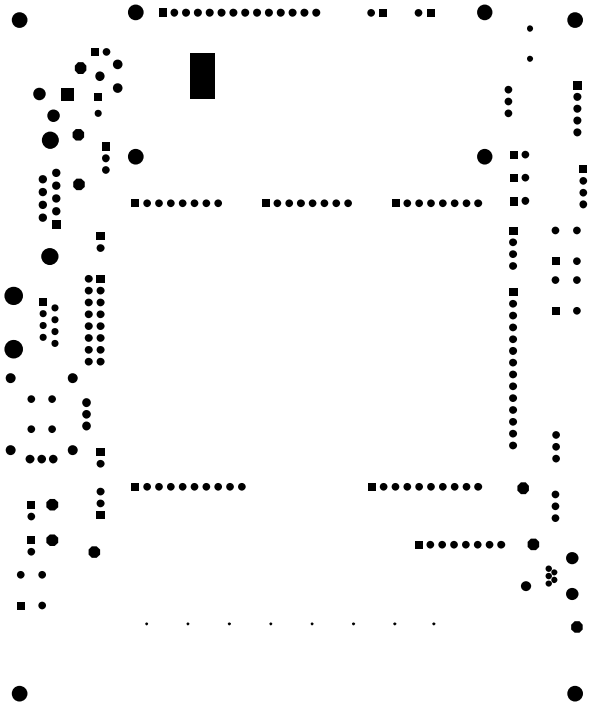
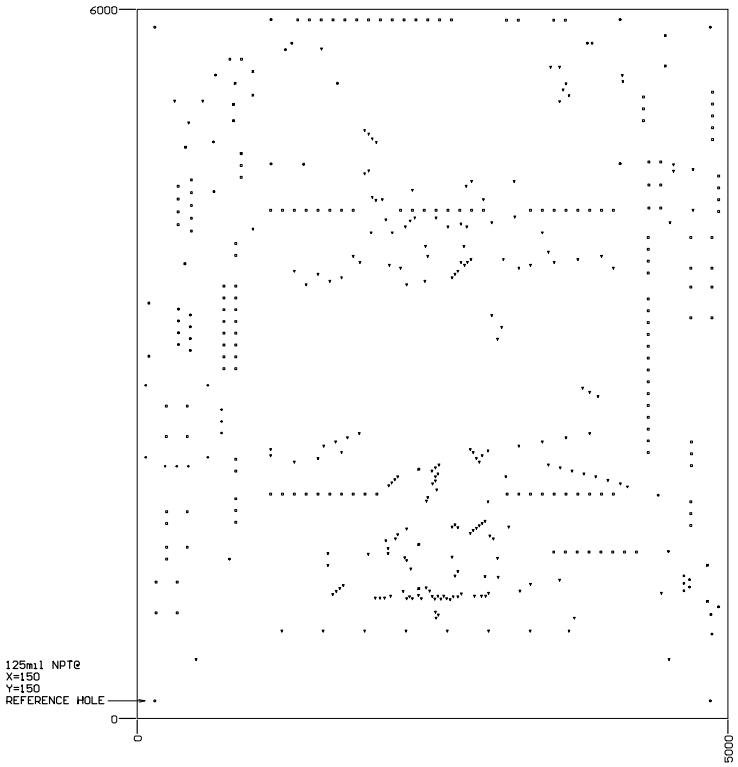


BOTTOM COPPER (.GBL)



BOTTOM SOLDERMASK (.GBS)



THROUGH HOLE

MARK	QTY	DIAM		PLTD	
•	199	10mil	0.254mm	PTH	Round
•	7	20mil	0.508mm	PTH	Round
•	5	28mil	0.7112mm	PTH	Round
•	7	32mil	0.8128mm	PTH	Round
•	8	35mil	0.889mm	PTH	Round
•	171	41mil	1.0414mm	PTH	Round
•	3	46mil	1.1684mm	PTH	Round
•	10	51.181mil	1.3mm	PTH	Round
•	7	63mil	1.6002mm	PTH	Round
•	3	67mil	1.7018mm	PTH	Round
•	2	82.677mil	2.1mm	PTH	Round
•	8	125mil	3.175mm	NPTH	Round
•	4	125mil	3.175mm	PTH	Round
•	1	150mil	3.81mm	PTH	Round
	435	Total			

NOTES:

1. MATERIAL: 2 LAYERS, FR4, 0.063 +/-10% IN. THK.
2. COPPER: 1/2 OUNCE PLATED TO 1 OUNCE FINISHED HASL.
3. SOLDERMASK: TWO SIDES, BLUE LPI.
   NOTE: APPLY SOLDERMASK PER FILES. .500 IN. DIAM BUTTONS AND ZIG-ZAG PATTERNED AREA ARE TO BE COVERED BY MASK.
4. HOLE SIZES: FINISHED SIZES LISTED.
   PLATING: AS LISTED.
   FINISHED SIZE AND LOCATION TOLERANCE: +/- .003 In.
5. FINISHED LINEAR TOLERANCES: +/- .010 .
6. SILKSCREEN: COMPONENT SIDE ONLY, WHITE EPOXY INK.

LAYER CONSTRUCTION - FILE IDENTIFICATION

DRILL AND TRIM(.GD1)

ALL DIM IN MILS

Cypress

ENGR: Mark Hastings (425) 787-4889

TITLE: Radon Eval Board

DWN:

PART NO: CY3214

REV: D

DATE: 24 AUG 06

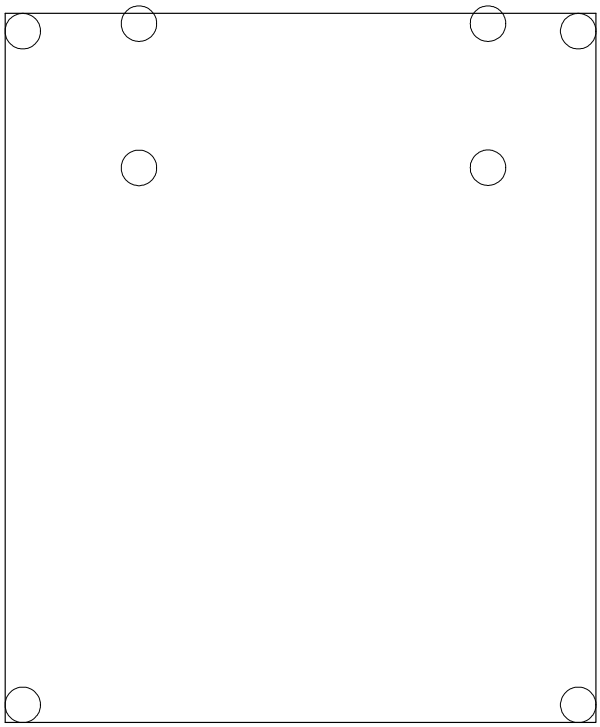
MATERIAL — SEE NOTES —

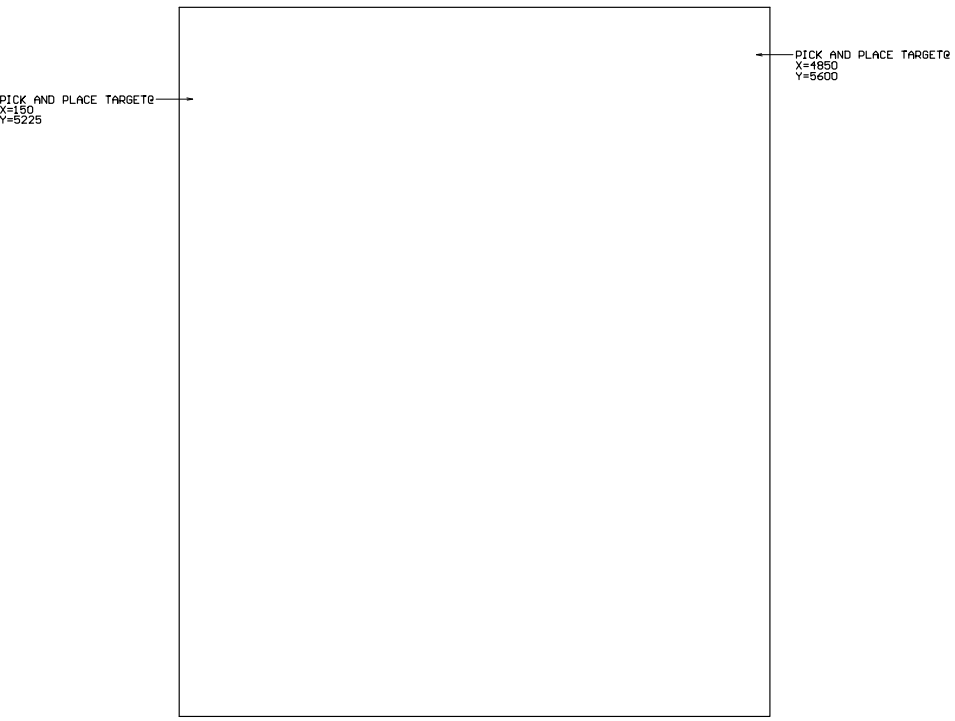
FILE NAME:

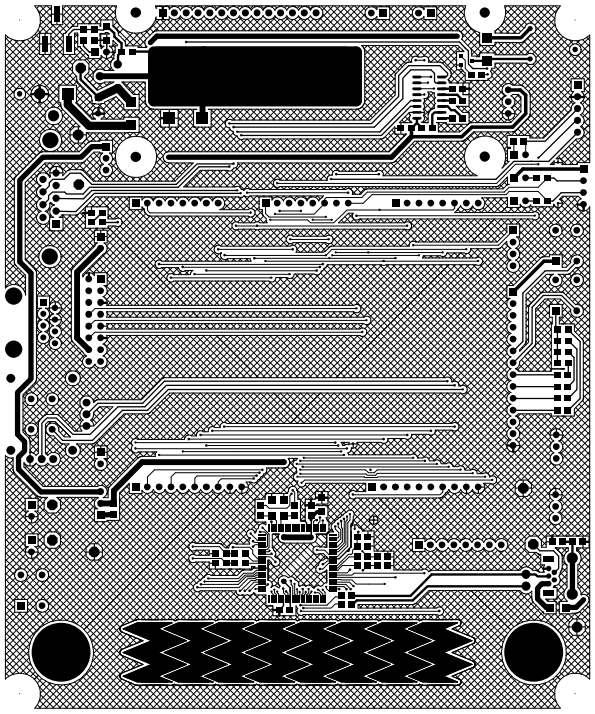
LAYER:

GERBER:

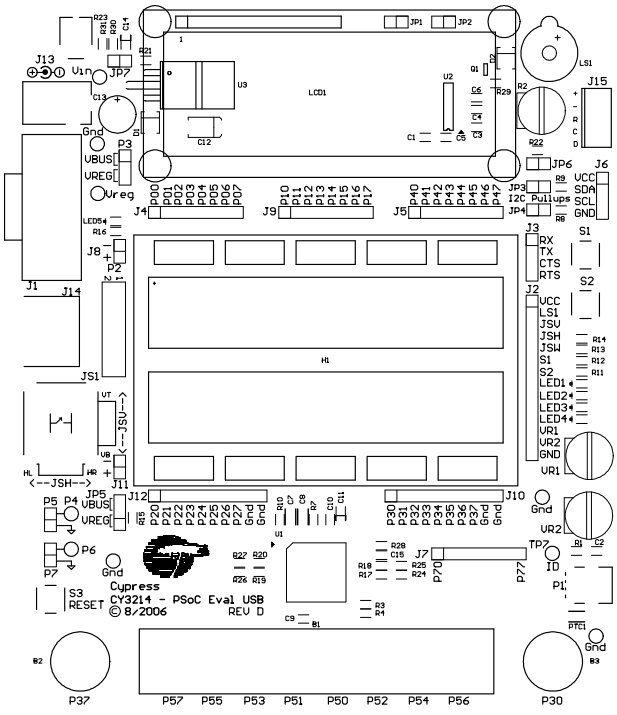
Cypress Semiconductor
2700 162nd St SW - BLDG D
Lynnwood, WA 98037
USA
meh@cypress.com



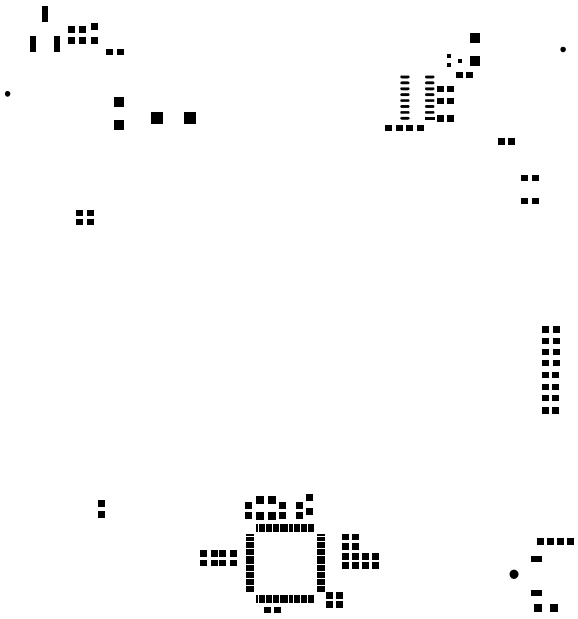

PICK AND PLACE TARGET@
X=4850
Y=5600
PICK AND PLACE TARGET@
X=150
Y=5225



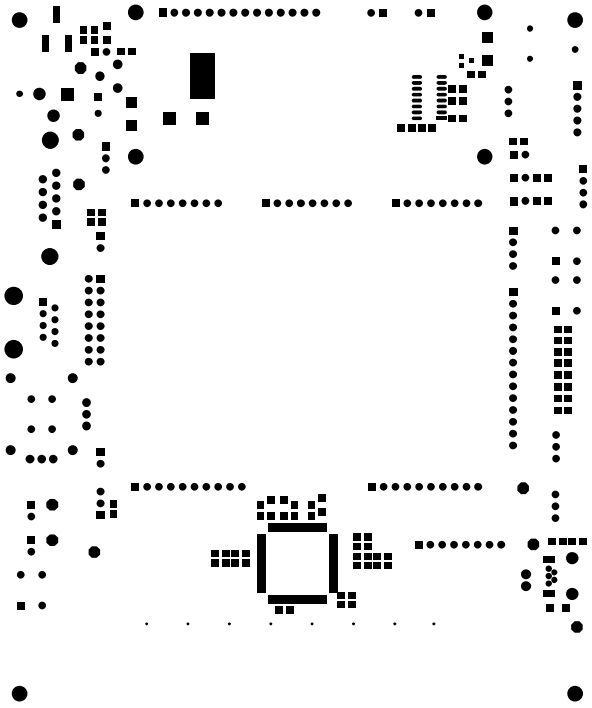
TOP COPPER (.GTL)



TOP OVERLAY (.GTO)



TOP PASTE MASK (.GTP)



TOP SOLDERMASK (.GTS)

